

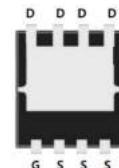


Features

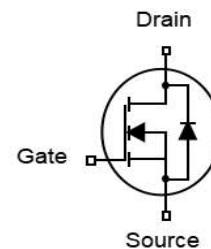
- N-Channel
- Low Crss
- Very low on -resistance RDS(ON)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 100% EAS Tested

V_{DS}	40	V
$R_{DS(on),TYP}$ @ $V_{GS}=10\text{ V}$	4.3	$\text{m}\Omega$
$R_{DS(on),TYP}$ @ $V_{GS}=4.5\text{ V}$	5.6	$\text{m}\Omega$
I_D	80	A

DFN5x6



Part ID	Package Type	Marking	Packing
ZT040N04G	DFN5x6	ZT040N04G	5000pcs/Reel



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit
Common Ratings (Tc=25°C Unless Otherwise Noted)			
V_{GS}	Gate-Source Voltage	± 20	V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	40	V
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
I_{DM}	Drain Current-Continuous@ Current-Pulsed (Note 1)	$T_c = 25^\circ\text{C}$	A

Mounted on Large Heat Sink

I_D	Drain Current-Continuous	$T_c = 25^\circ\text{C}$	80	A
		$T_c = 100^\circ\text{C}$	52	A
P_D	Maximum Power Dissipation		64	W
$R_{\theta JC}$	Thermal Resistance-Junction to Case		1.95	$^\circ\text{C}/\text{W}$

Drain-Source Avalanche Ratings

EAS	Avalanche Energy, Single Pulsed (Note 2)	210	mJ
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Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ $T_J=25^\circ\text{C}$ (unless otherwise stated)						
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	40	--	--	V
Idss	Zero Gate Voltage Drain Current	$V_{DS}=40\text{V}, V_{GS}=0\text{V}$	--	--	1	μA
IGSS	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	--	--	± 100	nA
VGS(th)	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0	1.6	2.5	V
RDS(on)	Drain-Source On-State Resistance	$V_{GS}=10\text{V}, I_D=20\text{A}$	--	4.3	5.2	$\text{m}\Omega$
RDS(on)	Drain-Source On-State Resistance	$V_{GS}=4.5\text{V}, I_D=15\text{A}$	--	5.6	7.8	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
Ciss	Input Capacitance	$V_{DS}=15\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	2676	--	pF
Coss	Output Capacitance		--	243	--	pF
Crss	Reverse Transfer Capacitance		--	221	--	pF
Rg	Gate Resistance	f=1MHz	--	1.7	--	Ω
Qg	Total Gate Charge	$V_{DS}=20\text{V}, I_D=30\text{A}, V_{GS}=10\text{V}$	--	56	--	nC
Qgs	Gate-Source Charge		--	9	--	nC
Qgd	Gate-Drain Charge		--	14	--	nC
Switching Characteristics						
Td(on)	Turn-on Delay Time	$V_{DS}=20\text{V}, I_D=30\text{A}, R_G=3.0\Omega, V_{GS}=10\text{V}$	--	7.5	--	ns
Tr	Turn-on Rise Time		--	16.5	--	ns
Td(off)	Turn-Off Delay Time		--	22.4	--	ns
Tf	Turn-Off Fall Time		--	13.2	--	ns
Source- Drain Diode Characteristics@ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
IS	Diode Forward Current	--	--	80	A	
ISM	Maximum Pulsed Drain-Source Diode Forward Current	--	--	320	A	
VSD	Forward on voltage ^(Note 3)	$I_S=20\text{A}, V_{GS}=0\text{V}$	--	--	1.2	V

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J = 25^\circ\text{C}$, $V_{DD} = 20\text{V}$, $V_G = 10\text{V}$, $R_G = 25\Omega$, $L = 0.5\text{mH}$.

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$



N- Channel Typical Characteristics

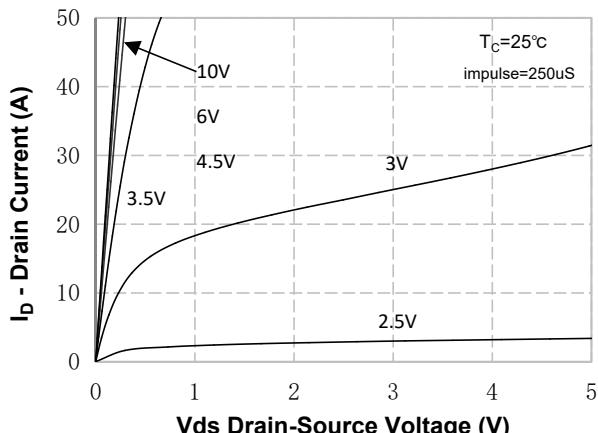


Figure 1. On-Region Characteristics

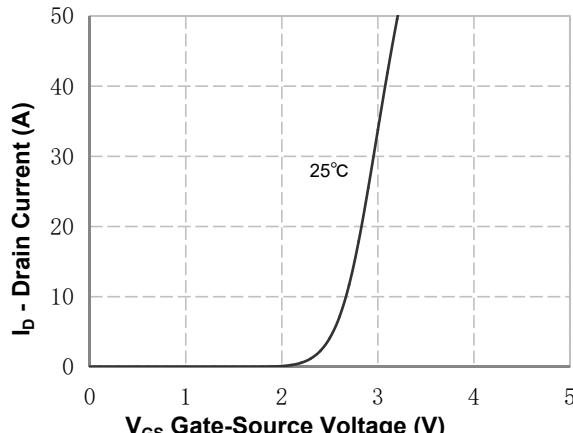


Figure 4. Transfer Characteristics

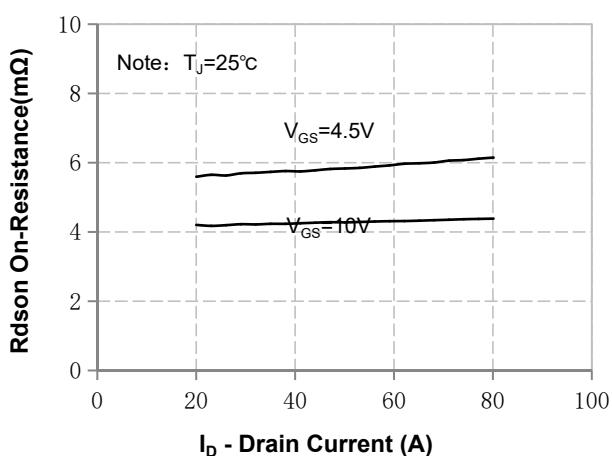


Figure 2. On-Resistance Variation vs Drain Current and Gate Voltage

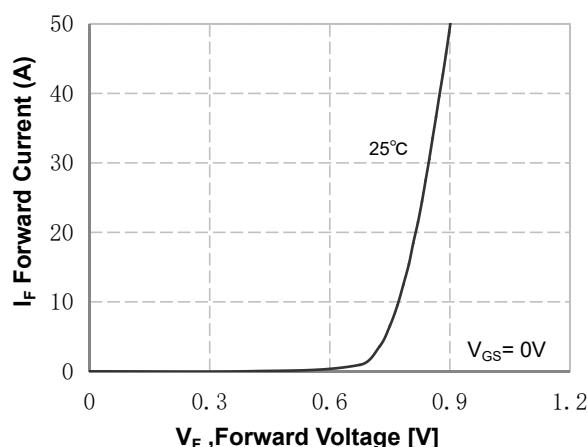


Figure 5. Body Diode Forward Voltage Variation with Source Current

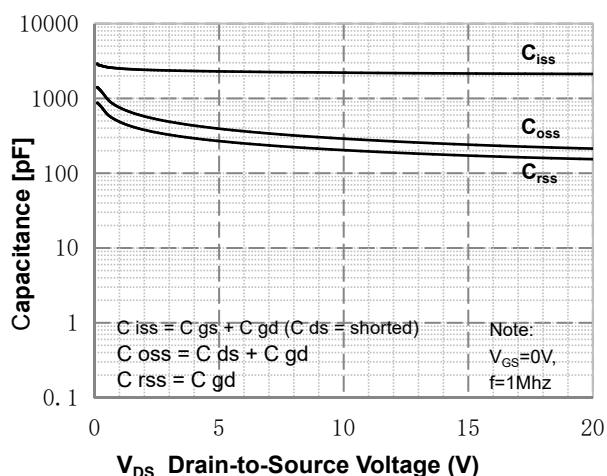


Figure 3. Capacitance Characteristics

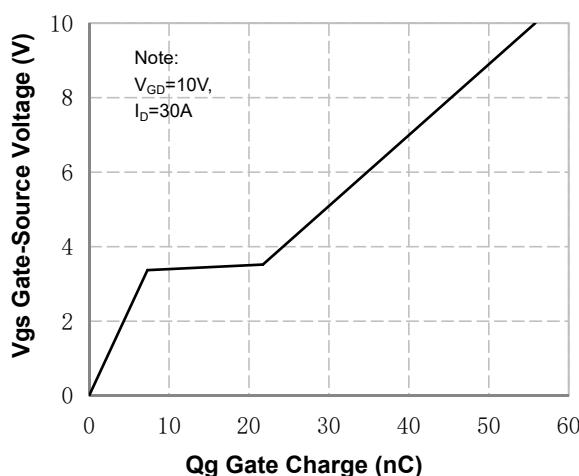


Figure 6. Gate Charge Characteristics

N Channel Typical Characteristics (Continued)

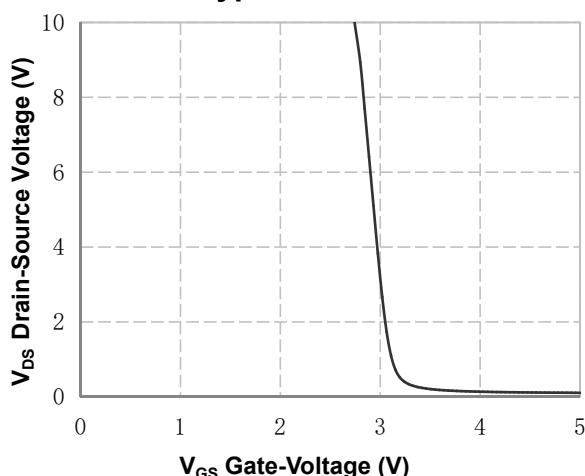


Figure 7. V_{DS} Drain-Source Voltage
vs Gate Voltage

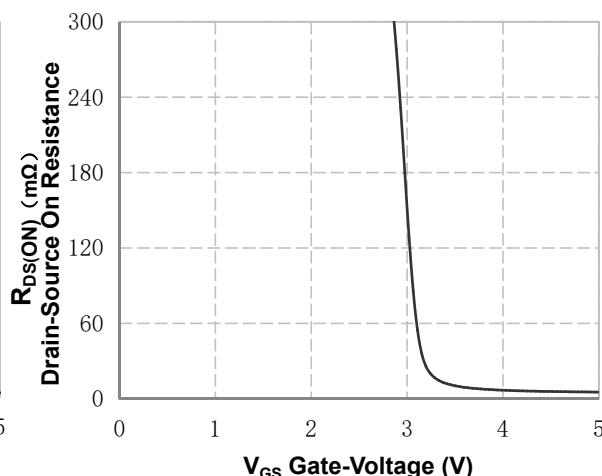


Figure 9. On-Resistance
vs Gate Voltage

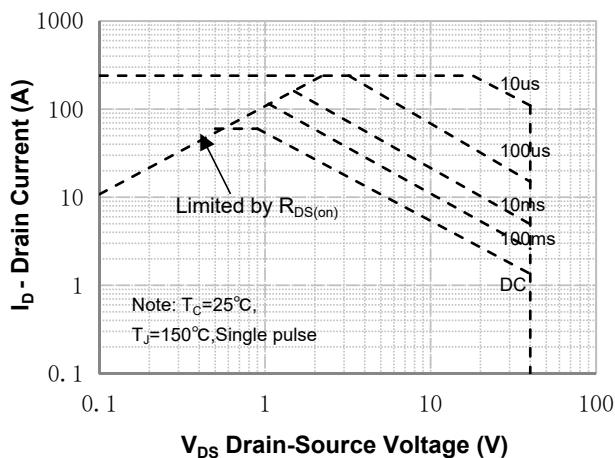


Figure 8. Maximum Safe Operating Area

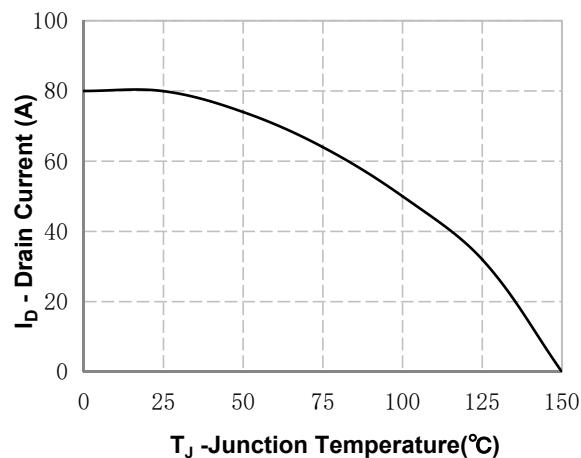


Figure 10. Maximum Continuous Drain Current vs Temperature

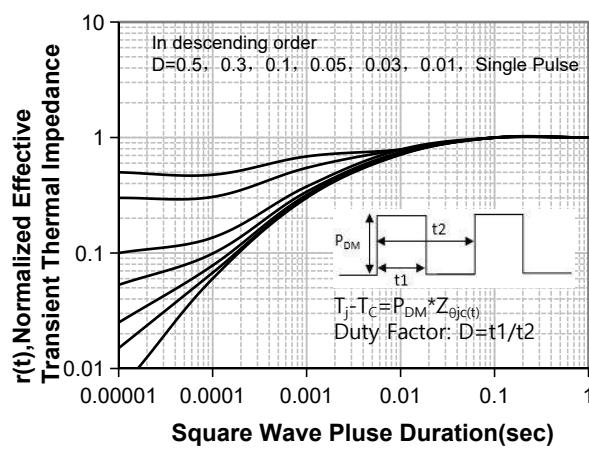
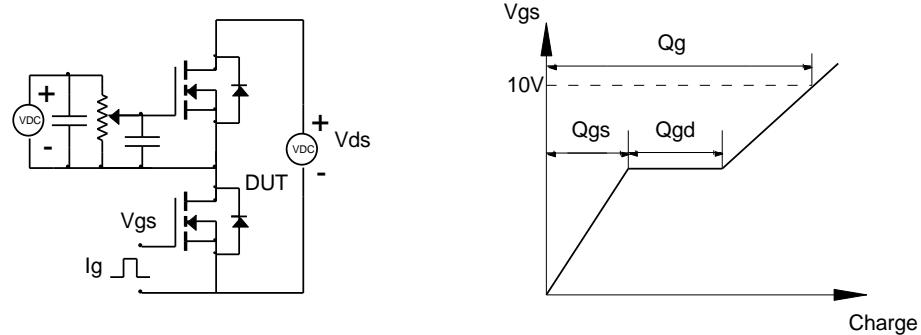


Figure 11. Transient Thermal Response Curve

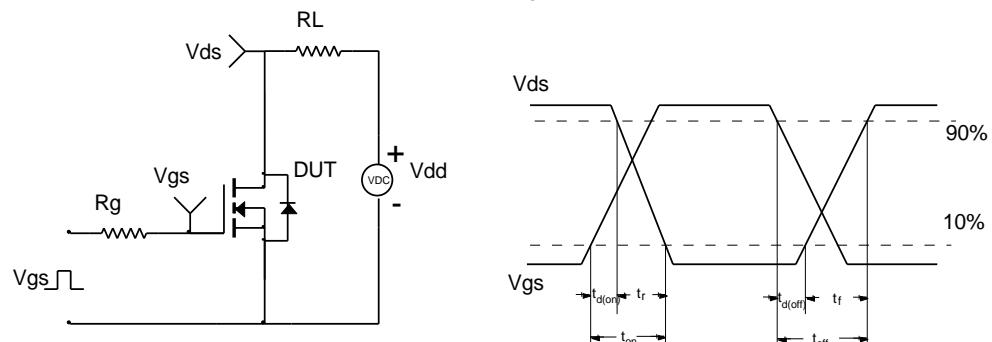


Test Circuit and Waveform

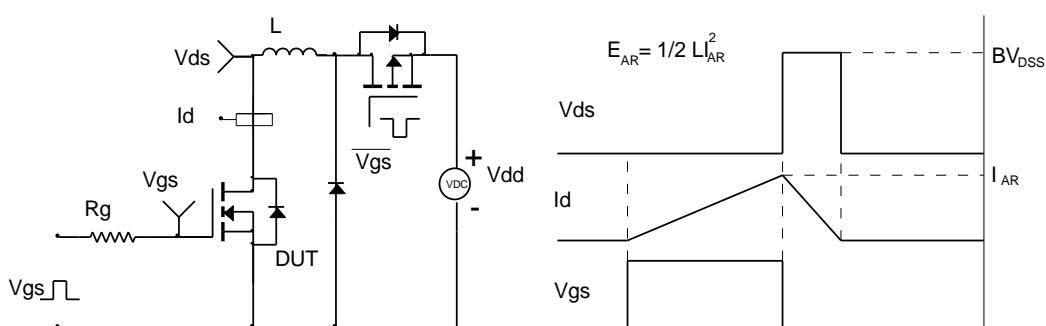
Gate Charge Test Circuit & Waveform



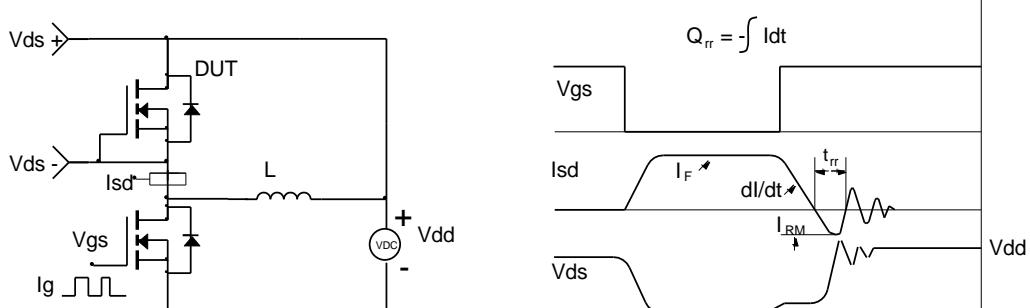
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

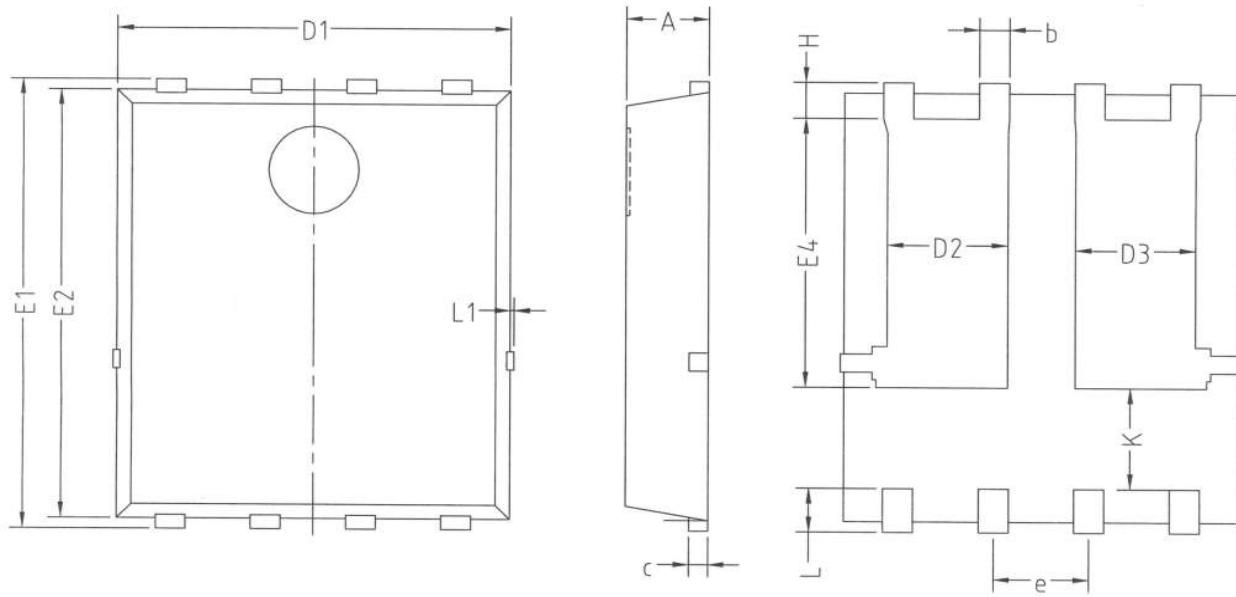


Diode Recovery Test Circuit & Waveforms





DFN5x6-8L Package Information



COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	1.00	1.10	1.20
b	0.30	0.40	0.50
c	0.154	0.254	0.354
D1	5.00	5.20	5.40
D2	1.40	1.60	1.80
D3	1.40	1.60	1.80
e	1.27BSC		
E1	5.95	6.15	6.35
E2	5.66	5.86	6.06
E4	3.47	3.67	3.87
H	0.40	0.50	0.60
K	1.23	1.38	1.53
L	0.30	0.60	0.70
L1			0.12

Customer Service

Sales and Service:

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